

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)}$	I_D $T_A = +25^\circ C$
60V	66m Ω @ $V_{GS} = 10V$	5.0A
	97m Ω @ $V_{GS} = 4.5V$	4.1A

Description and Applications

This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

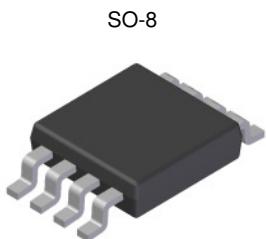
- Motor Control
- Backlighting
- DC-DC Converters
- Power Management Functions

Features and Benefits

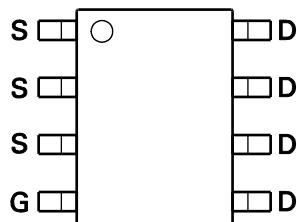
- Low on-resistance
- Fast switching speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

Mechanical Data

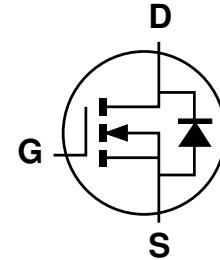
- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram Below
- Terminals: Finish – Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.074 grams (Approximate)



Top View



Top View



Equivalent Circuit

Ordering Information (Notes 4 & 5)

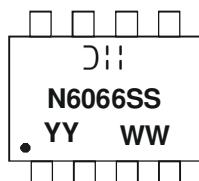
Part Number	Compliance	Case	Packaging
DMN6066SSS-13	Commercial	SO-8	2,500/Tape & Reel
DMN6066SSSQ-13	Automotive	SO-8	2,500/Tape & Reel

Notes:

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product_grade_definitions/.
5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

SO-8



○II = Manufacturer's Marking
 N6066SS = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 09 = 2009)
 WW = Week (01 - 53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Drain-Source Voltage		V_{DSS}	60	V
Gate-Source Voltage	(Note 6)	V_{GS}	± 20	V
Single Pulsed Avalanche Energy	(Note 11)	E_{AS}	37.5	mJ
Single Pulsed Avalanche Current	(Note 11)	I_{AS}	5.0	A
Continuous Drain Current	$V_{GS} = 10\text{V}$	I_D	5.0	A
			4.0	
			3.7	
Pulsed Drain Current	$V_{GS} = 10\text{V}$	I_{DM}	23	A
Continuous Source Current (Body diode)	(Note 8)	I_S	4.0	A
Pulsed Source Current (Body diode)	(Note 9)	I_{SM}	23	A

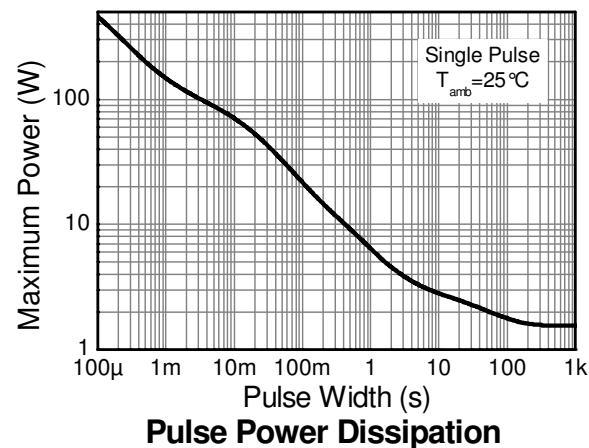
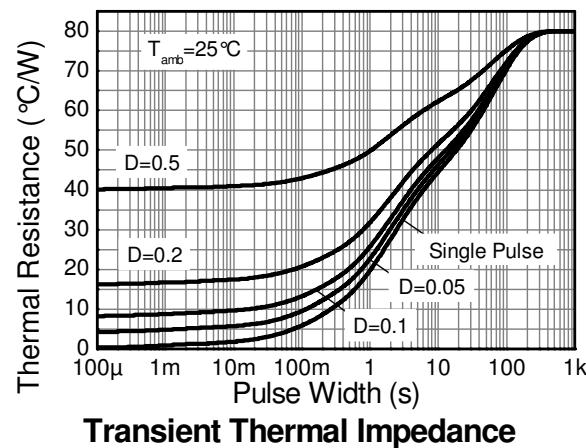
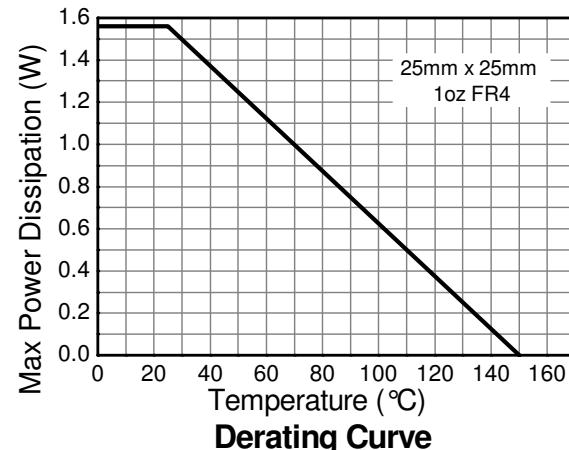
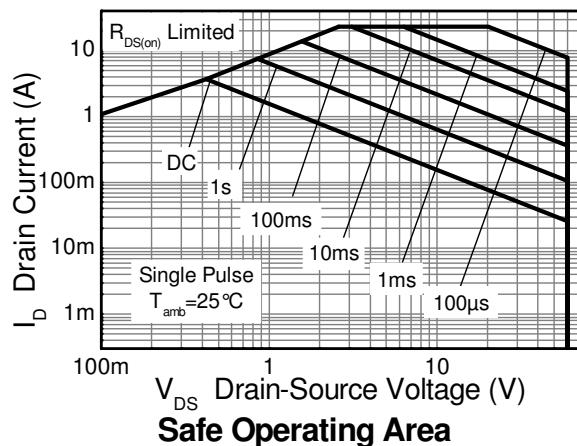
Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Note 7)	P_D	1.56	W mW/ $^\circ\text{C}$
			12.5	
	(Note 8)		2.81	
Thermal Resistance, Junction to Ambient	(Note 7)	$R_{\theta JA}$	80.0	$^\circ\text{C/W}$
	(Note 8)		44.5	
Thermal Resistance, Junction to Lead	(Note 10)	$R_{\theta JL}$	37.0	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Notes:

6. AEC-Q101 V_{GS} maximum is $\pm 16\text{V}$.
7. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
8. Same as note (7), except the device is measured at $t \leq 10$ sec.
9. Same as note (7), except the device is pulsed with $D = 0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.
10. Thermal resistance from junction to solder-point (at the end of the drain lead).
11. UIS in production with $L = 3.0\text{mH}$, $I_{AS} = 5.0\text{A}$, $R_G = 25\Omega$, $V_{DD}=50\text{V}$, starting $T_J = +25^\circ\text{C}$.

Thermal Characteristics



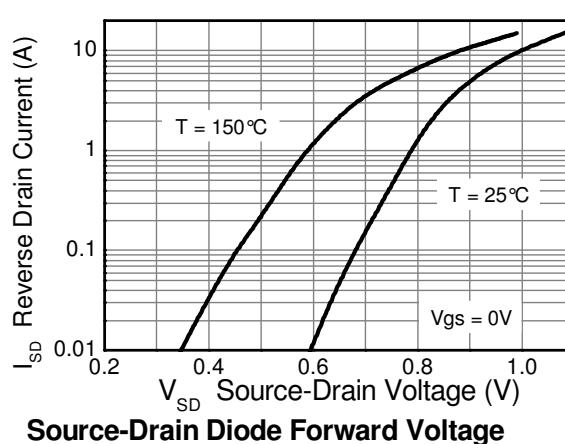
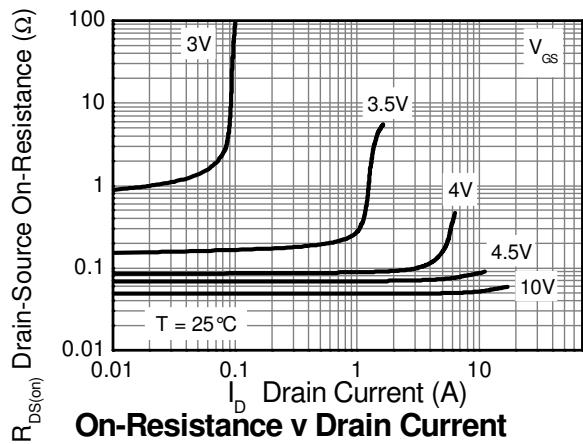
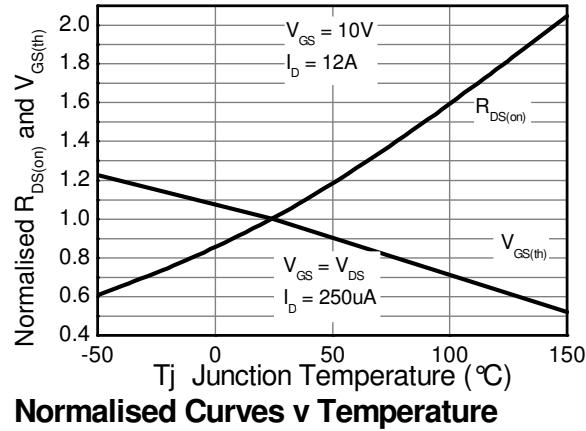
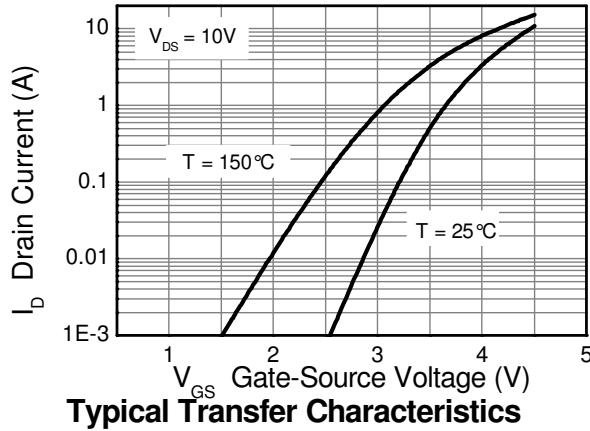
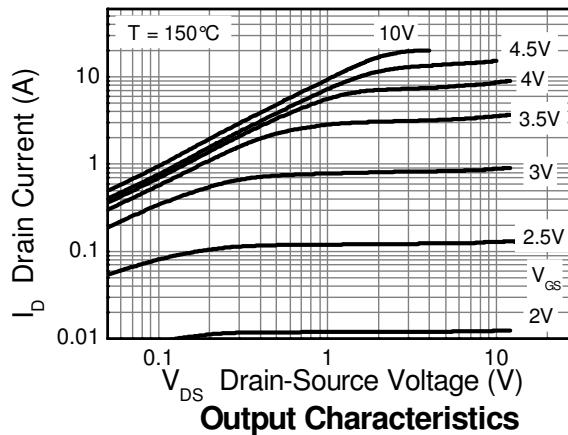
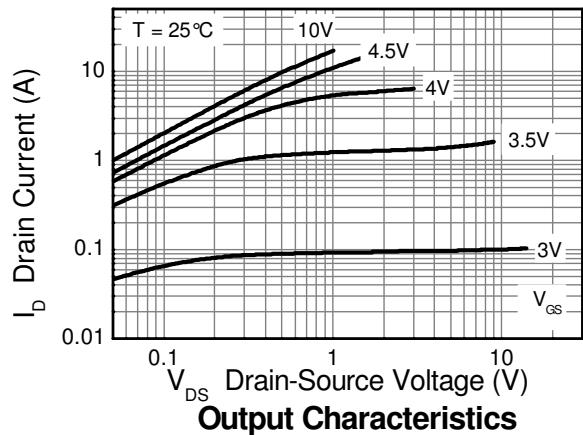
Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	60	—	—	V	$I_D = 250\mu\text{A}$, $V_{\text{GS}} = 0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	0.5	μA	$V_{\text{DS}} = 60\text{V}$, $V_{\text{GS}} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 100	nA	$V_{\text{GS}} = \pm 20\text{V}$, $V_{\text{DS}} = 0\text{V}$
ON CHARACTERISTICS						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	1.0	—	3.0	V	$I_D = 250\mu\text{A}$, $V_{\text{DS}} = V_{\text{GS}}$
Static Drain-Source On-Resistance (Note 12)	$R_{\text{DS}(\text{ON})}$	—	0.048	0.066	Ω	$V_{\text{GS}} = 10\text{V}$, $I_D = 4.5\text{A}$
			0.068	0.097		$V_{\text{GS}} = 4.5\text{V}$, $I_D = 3.5\text{A}$
Forward Transconductance (Notes 12 & 13)	g_{fs}	—	19.2	—	S	$V_{\text{DS}} = 15\text{V}$, $I_D = 6\text{A}$
Diode Forward Voltage (Note 12)	V_{SD}	—	0.89	1.15	V	$I_S = 4.5\text{A}$, $V_{\text{GS}} = 0\text{V}$
Reverse Recovery Time (Note 13)	t_{rr}	—	23	—	ns	$I_S = 2.4\text{A}$, $di/dt = 100\text{A}/\mu\text{s}$
Reverse Recovery Charge (Note 13)	Q_{rr}	—	19.7	—	nC	
DYNAMIC CHARACTERISTICS (Note 13)						
Input Capacitance	C_{iss}	—	502	—	pF	$V_{\text{DS}} = 30\text{V}$, $V_{\text{GS}} = 0\text{V}$ $f = 1\text{MHz}$
Output Capacitance	C_{oss}	—	45.7	—	pF	
Reverse Transfer Capacitance	C_{rss}	—	27.1	—	pF	
Total Gate Charge (Note 14)	Q_g	—	5.4	—	nC	$V_{\text{GS}} = 4.5\text{V}$ $V_{\text{GS}} = 10\text{V}$ $I_D = 4.5\text{A}$
Total Gate Charge (Note 14)	Q_g	—	10.3	—	nC	
Gate-Source Charge (Note 14)	Q_{gs}	—	1.7	—	nC	
Gate-Drain Charge (Note 14)	Q_{gd}	—	3.2	—	nC	
Turn-On Delay Time (Note 14)	$t_{\text{D}(\text{on})}$	—	2.7	—	ns	$V_{\text{DD}} = 30\text{V}$, $V_{\text{GS}} = 10\text{V}$ $I_D = 1\text{A}$, $R_G \geq 6.0\Omega$
Turn-On Rise Time (Note 14)	t_r	—	2.4	—	ns	
Turn-Off Delay Time (Note 14)	$t_{\text{D}(\text{off})}$	—	14.7	—	ns	
Turn-Off Fall Time (Note 14)	t_f	—	5.4	—	ns	

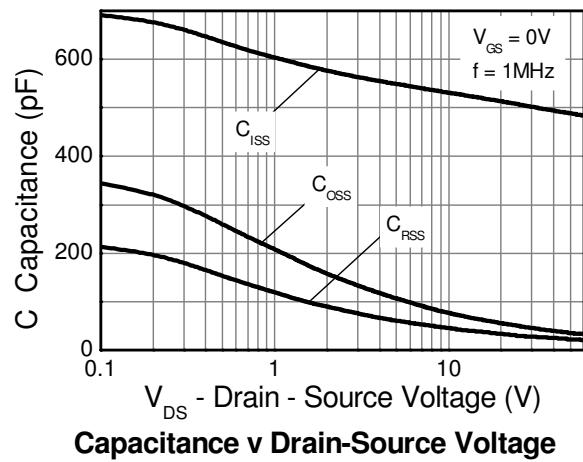
Notes:

12. Measured under pulsed conditions. Pulse width $\leq 300\mu\text{s}$; duty cycle $\leq 2\%$.
13. For design aid only, not subject to production testing.
14. Switching characteristics are independent of operating junction temperatures.

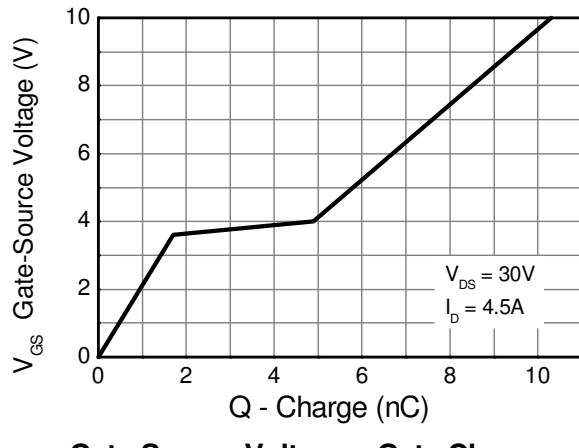
Typical Characteristics



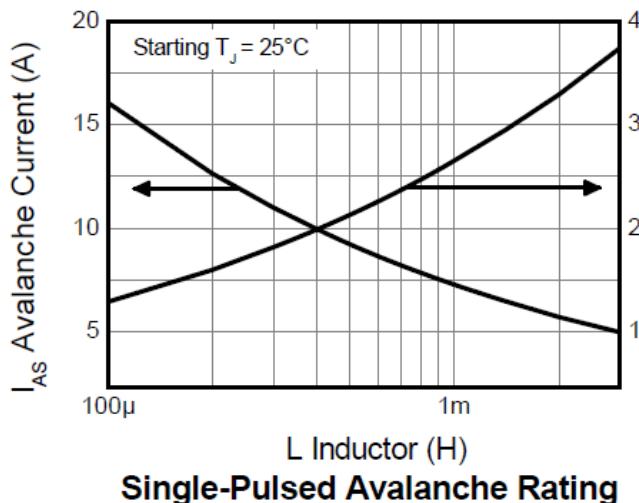
Typical Characteristics (continued)



Capacitance v Drain-Source Voltage

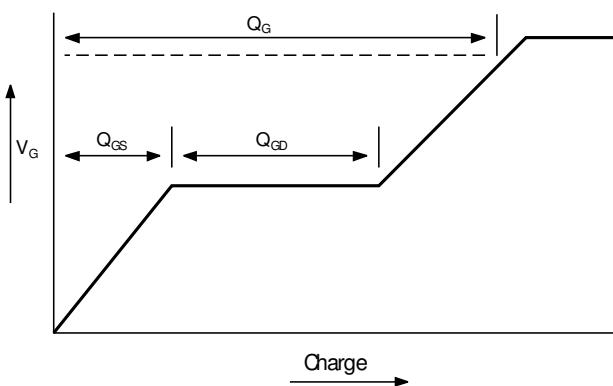


Gate-Source Voltage v Gate Charge

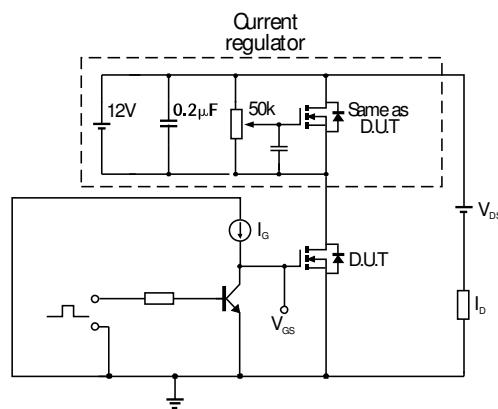


Single-Pulsed Avalanche Rating

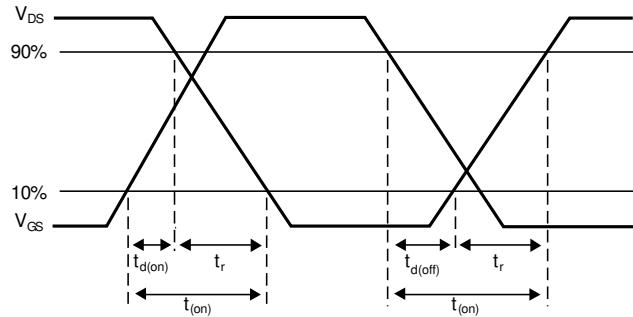
Test Circuits



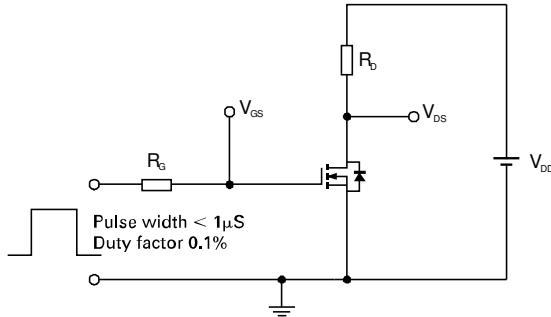
Basic gate charge waveform



Gate charge test circuit



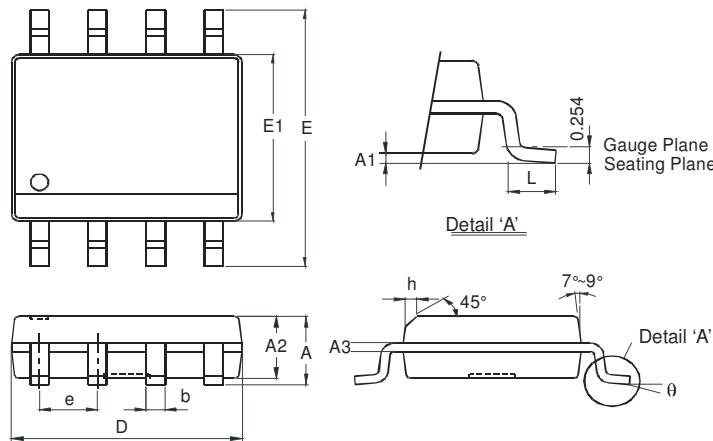
Switching time waveforms



Switching time test circuit

Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.

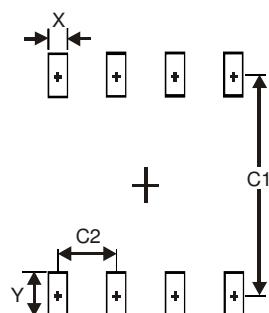


SO-8		
Dim	Min	Max
A	-	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27	Typ
h	-	0.35
L	0.62	0.82
θ	0°	8°

All Dimensions in mm

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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